



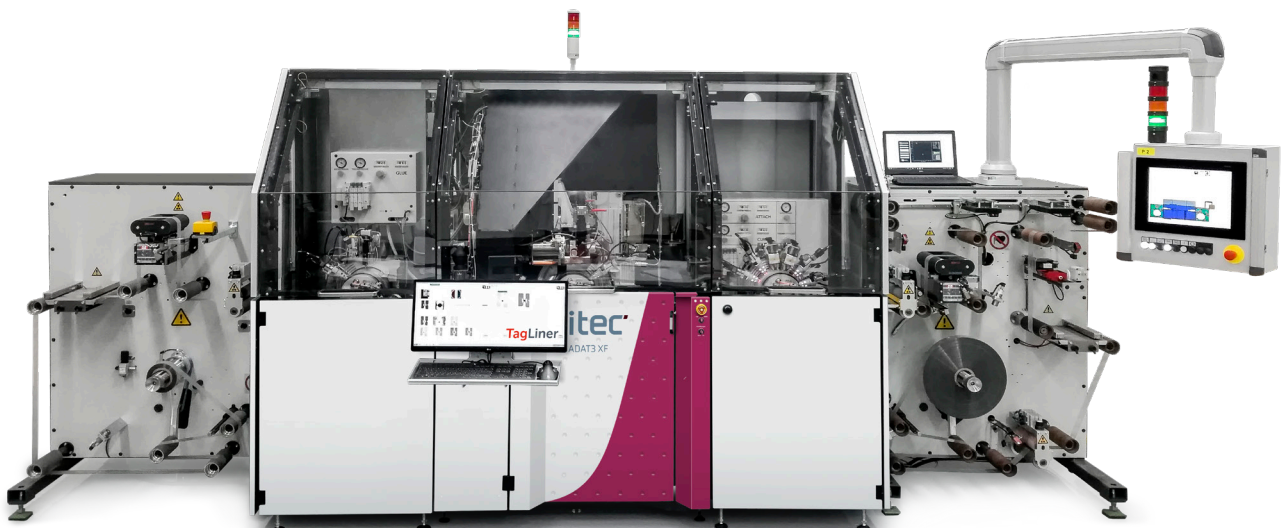
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ADAT3 XF TagLiner High-Volume RFID Inlay Die Bonding

For the highest productivity and quality standard at the lowest cost of ownership.

Curing in milliseconds versus seconds in the current industry practice, the ADAT3 XF TagLiner is three times faster and 30% more accurate than anything on the market. Average systems only work with transparent web material; this TagLiner handles a

diverse range, including opaque for sustainability - enabling you to move away from PET plastics. Eliminating manual handling through automated wafer change and qualified for die bond of all known ICs down to 200um die size. The ADAT3 XF TagLiner performs a complete inspection without sacrificing speed and productivity.



Key Features

- Performance: 48000 units per hour with the machine speed up to 50.8 mm web pitch
- High-precision die-attach
- Works with both transparent and non-transparent web material
- High-precision glue dispense system
- High-speed thermal compression curing system. Easy maintenance, one or two units only
- 100% high-resolution optical inspections on glue, die, attach and cure processes - without compromising machine speed
- Process fully qualified for major chip suppliers at the industry's tightest reliability requirements: temperature, humidity, and mechanical
- 8 to 12 inches wafer compatible with fully automatic wafer change
- Capable to handle dies down to 200 μm
- Single-track design for easy operation and change over
- Integrated with BW Paper systems, winding/conversion systems, and Voyantic readers

Specifications

Speed:	48000 units per hour flip chip up to a web pitch of 50.8 mm
Die size:	200 x 200 μm to 5 x 5 mm
Web width:	40-165 mm, single row operation
Subsystems:	BW Paper Systems Winder/Unwinder Voyantic Reader
Machine dimensions:	Length, width, height: 5397 x 1500 x 2617 mm ³ Net weight: 5230 kg
Placement accuracy:	Dispense accuracy:
<ul style="list-style-type: none"> • Die position: x, y: $1\sigma < 9\mu\text{m}$ • Die rotation: φ: $1\sigma < 0.67^\circ$ • Pick and place force: $0.2-1.5 \pm 0.1 \text{ N}$ 	<ul style="list-style-type: none"> • Dot size accuracy: $1\sigma < 10 \mu\text{m}$ • Dot position accuracy: $1\sigma < 10 \mu\text{m}$ • Dot diameter: $>200 \mu\text{m}$
Cure system:	QA vision inspections:
<ul style="list-style-type: none"> • 2 stitch units, thermo compression cure • Cure temperature range: $20 \dots 500 \pm 5^\circ\text{C}$ • Cure force range: $0-20 \pm 0.5 \text{ N}$ • Cure time range: $0-5000 \text{ ms}$ 	<ul style="list-style-type: none"> • Glue dot size and -location • Die top-side before attach • Die bottom-side before attach • Glue presence before attach • Die presence before cure • Die placement and rotation
Wafer handling:	
<ul style="list-style-type: none"> • 8 and 12 inches • Steel/plastic Film Frame Carrier (FFC) • Automatic wafer change • Wafer expansion • Automatic barcode reader 	

Contact itec_sales@itecequipment.com to learn more about the ADAT3 XF TagLiner

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